Washtenaw Community College Comprehensive Report

ELE 121 Hand Soldering Techniques Effective Term: Fall 2025

Course Cover

College: Advanced Technologies and Public Service Careers Division: Advanced Technologies and Public Service Careers Department: Advanced Manufacturing Discipline: Electricity/Electronics Course Number: 121 Org Number: 14430 Full Course Title: Hand Soldering Techniques Transcript Title: Hand Soldering Techniques Is Consultation with other department(s) required: No Publish in the Following: College Catalog , Time Schedule , Web Page Reason for Submission: New Course Change Information: Rationale: New course Proposed Start Semester: Fall 2025 Course Description: In this course, students will gain a theoretical understanding of the materials, tools,

Course Description: In this course, students will gain a theoretical understanding of the materials, tools, and techniques used, as well as hands-on training in through-hole and surface-mount soldering. Students will also learn industry recognized standards, inspection techniques, and how to repair faulty solder joints. The use of a stereo microscope for post-repair visual inspection will also be explored. This course prepares students to sit for the Institute of Printed Circuits (IPC) basic CIS certification (Certified IPC Specialist).

Course Credit Hours

Variable hours: No Credits: 2 Lecture Hours: Instructor: 15 Student: 15 Lab: Instructor: 30 Student: 30 Clinical: Instructor: 0 Student: 0

Total Contact Hours: Instructor: 45 Student: 45 Repeatable for Credit: NO Grading Methods: Letter Grades Are lectures, labs, or clinicals offered as separate sections?: NO (same sections)

College-Level Reading and Writing

College-level Reading & Writing

College-Level Math No Level Required

Requisites Prerequisite ELE 111 minimum grade "C"

General Education

<u>Request Course Transfer</u> Proposed For:

Student Learning Outcomes

1. Describe the basic principles of soldering.

Assessment 1

Assessment Tool: Outcome-related multiple-choice and short answer exam questions Assessment Date: Fall 2027 Assessment Cycle: Every Three Years Course section(s)/other population: All Number students to be assessed: All How the assessment will be scored: Answer key and rubric Standard of success to be used for this assessment: 70% of students will score 70% or higher. Who will score and analyze the data: Departmental faculty

2. Identify industry-recognized standards for acceptable solder joints.

Assessment 1

Assessment Tool: Outcome-related exam questions Assessment Date: Fall 2027 Assessment Cycle: Every Three Years Course section(s)/other population: All Number students to be assessed: All How the assessment will be scored: Answer key Standard of success to be used for this assessment: 70% of students will score 70% or higher. Who will score and analyze the data: Departmental faculty

3. Create acceptable through-hole and surface mount solder joints.

Assessment 1

Assessment Tool: Outcome-related demonstration Assessment Date: Fall 2027 Assessment Cycle: Every Three Years Course section(s)/other population: All Number students to be assessed: All How the assessment will be scored: Rubric Standard of success to be used for this assessment: 70% of students will score 70% or higher. Who will score and analyze the data: Departmental faculty

4. Assess the quality of solder joints using industry standard visual inspection techniques.

Assessment 1

Assessment Tool: Outcome-related demonstration Assessment Date: Fall 2027 Assessment Cycle: Every Three Years Course section(s)/other population: All Number students to be assessed: All How the assessment will be scored: Checklist Standard of success to be used for this assessment: 70% of students will score 70% or higher. Who will score and analyze the data: Departmental faculty

5. Repair faulty solder joints.

Assessment 1

Assessment Tool: Outcome-related demonstration Assessment Date: Fall 2027

- Assessment Cycle: Every Three Years
- Course section(s)/other population: All
- Number students to be assessed: All
- How the assessment will be scored: Rubric
- Standard of success to be used for this assessment: 70% of students will score 70% or higher. Who will score and analyze the data: Departmental faculty

Course Objectives

- 1. Explain how concepts such as heat transfer and melting point affect solder joint quality.
- 2. Identify types of solder, their properties, and applications.
- 3. Identify types of solder flux, their properties, and applications.
- 4. Explain the purpose of soldering tools and equipment.
- 5. Describe materials and components used in electronic soldering.
- 6. Identify industry recognized standards and requirements.
- 7. Demonstrate preparation of electronic components and printed circuit boards (PCBs) for soldering.
- 8. Demonstrate proper techniques for heating, applying solder, and ensuring good solder flow for both through-hole and surface mount technology (SMT) soldering.
- 9. Demonstrate techniques for soldering multi-lead devices like integrated circuits (IC) and connectors.
- 10. Demonstrate techniques for soldering heat-sensitive components.
- 11. Explain methods used for visual inspection of solder joints.
- 12. Demonstrate the use of industry standards and inspection techniques to identify acceptable and unacceptable solder joints.
- 13. Demonstrate de-soldering techniques.
- 14. Demonstrate repairs of cold and bridged joints.
- 15. Demonstrate rework of multi-lead and fine-pitch devices.
- 16. Demonstrate post-repair inspection and testing techniques.

New Resources for Course

Course Textbooks/Resources

Textbooks Manuals Periodicals Software

Equipment/Facilities

Action	Date
Faculty Preparer	Oct 28, 2024
Recommend Approval	Oct 29, 2024
Recommend Approval	Oct 30, 2024
Recommend Approval	Feb 11, 2025
Recommend Approval	Feb 13, 2025
Approve	Feb 14, 2025
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